

ABSTRACT OF THE DISCLOSURE

A radiation sensitive composition useful as a photoresist containing a resin composition and a radiation sensitive material, wherein the resin composition comprises a mixture of two or more resins different from each other by at least 0.03 in refractive index or comprises a resin component of an alkali-soluble resin and a resin additive of a resin working as a dissolution inhibitor for the radiation sensitive composition, such as an acrylic polymer, a methacrylic polymer or a styrenic polymer. A dissolution rate in a 2.38 weight-% aqueous tetramethylammonium hydroxide solution of the radiation sensitive composition is preferably 5000 Å/min or less. Use of these resin compositions enable one to reduce the amount of the quinonediazide radiation sensitive agents to be used and obtain a radiation sensitive composition which has both high sensitivity and highly normalized film remaining characteristics.